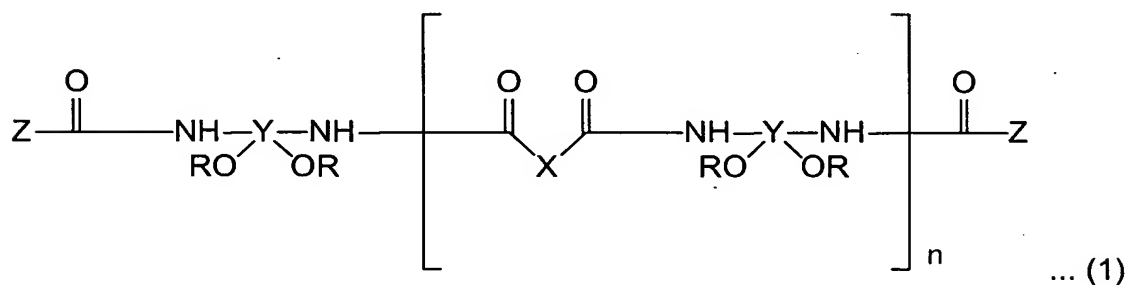


WHAT IS CLAIMED IS:

1. A photosensitive resin composition comprising:

(A) a heat-resistant polymer represented by general formula (1)



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where X represents a divalent organic group; Y represents a tetravalent organic group; Z represents a cyclic compound group free of reactive unsaturated bonds; R represents hydrogen or a monovalent organic group; and n is an integer of 2 to 500 and represents the number of repeating units of the polymer;

10

(B) a photoreactive compound; and

(C) a solvent.

2. The photosensitive resin composition according to claim 1, wherein at

15

least one of the organic groups X and Y is an aromatic group.

3. The photosensitive resin composition according to claim 1, wherein the cyclic compound group Z is a compound group having an alicyclic structure.

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4. The photosensitive resin composition according to claim 2, wherein the cyclic compound group Z is a compound group having an alicyclic structure.
- 5 5. The photosensitive resin composition according to claim 3, wherein the compound group having an alicyclic structure has 3 or 4 carbon atoms.
6. The photosensitive resin composition according to claim 4, wherein the compound group having an alicyclic structure has 3 or 4 carbon atoms.
- 10 7. The photosensitive resin composition according to claim 1, wherein the divalent organic group represented by X comprises at least one divalent group derived from 3-fluoroisophthalic acid, 2-fluoroisophthalic acid, 3-fluorophthalic acid, 2-fluorophthalic acid, 2,4,5,6-tetrafluoroisophthalic acid, 15 3,4,5,6-tetrafluorophthalic acid, 4,4'-hexafluoroisopropylidenediphenyldicarboxylic acid, perfluorosuberic acid, 2,2'-bis(trifluoromethyl)-4,4'-biphenylenedicarboxylic acid, terephthalic acid, isophthalic acid, 4,4'-oxydiphenyldicarboxylic acid, 5-nitroisophthalic acid, 1,4-naphthalenedicarboxylic acid, 2,6-naphthalenedicarboxylic acid, and 20 4,4'-biphenyldicarboxylic acid.
8. The photosensitive resin composition according to claim 1, wherein the tetravalent organic group represented by Y comprises at least one divalent group derived from 4,4'-diamino-3,3'-dihydroxybiphenyl, 25 2,2'-bis(3-amino-4-hydroxyphenyl)propane, and

2,2'-bis(3-amino-4-hydroxyphenyl)hexafluoropropane.

9. The photosensitive resin composition according to claim 1, wherein Z comprises at least one group selected from the group consisting of
5 cyclopropyl, cyclobutyl, 2-phenyl-1-cyclopropyl, 1-phenyl-1-cyclopropyl, 1-benzocyclobutenyl, 2-methylcyclopropenyl, 1-hydroxy-1-cyclopropyl, 1-carboxy-1-cyclopropyl, and 1-carboxy-1-cyclobutyl.

10. The photosensitive resin composition according to claim 1, wherein
10 the heat-resistant polymer has a weight average molecular weight in the range of 5,000 to 80,000.

11. A process for forming a relief pattern, comprising:
applying the photosensitive resin composition according to claim 1 to
15 a support substrate and drying the composition applied to form a photosensitive resin film;
subjecting the dried photosensitive resin film to exposure;
subjecting the exposed photosensitive resin film to development using an alkaline aqueous solution; and
20 subjecting the developed photosensitive resin film to heating treatment.

12. An electronic component having an electronic device including at least an interlayer dielectric film layer and a surface protecting film layer,
25 wherein at least one of the interlayer dielectric film layer and the

surface protecting film layer comprises a resin film formed from the photosensitive resin composition according to claim 1.

13. The electronic device according to claim 12, wherein the resin film
5 comprises a patterned film formed by the process according to claim 11.